

## **AN INTEGRATED CIRCUIT AND A METHOD OF MANUFACTURING AN INTEGRATED CIRCUIT**

### **ABSTRACT**

An apparatus and process to assess the occurrence or the likelihood of a failure in an integrated circuit. The process includes forming a conductive region such as a runner about the periphery of a substrate or die. The conductive regions may be located at one or more different metallization layers within the integrated circuit. The conductive region is coupled to one or more of the bond pads. The die is assessed by measuring the resistance, conductivity, cross talk or other electrical characteristics on the conductive region via the bond pads. The assessment can then be used to predict whether, for example, the runners formed in the integrated circuit have failed or are likely to fail.

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